



Specifications

Insulation Resistance: 10,000MΩ min. at 100V DC
Withstanding Voltage: 100V AC for 1 minute
Contact Resistance: 100mΩ or less
Operating Temp.Range: -40°C to +150°C

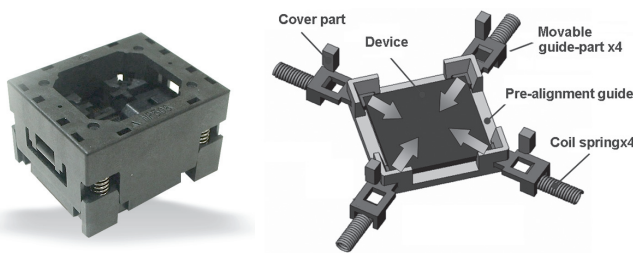
Materials and Finish

Housing: Polyetherimide (PEI), glass-filled
Polyethersulphone (PES), glass-filled
Contacts: Beryllium Copper (BeCu)
Plating: Gold over Nickel

Open Top Types NP506
Specifications / Material and Finish
(see above)

Features

- Active alignment for IC package positioning



Open Top Types NP404
Specifications / Material and Finish
(see above)

Features

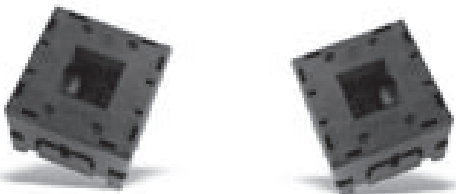
- Buckling Beam contacts



Open Top Types NP473 and NP364
Specifications / Material and Finish
(see above)

Features

- 0.50 and 1.00 mm pitch
- Buckling Beam contacts
- Low actuation force

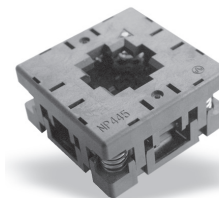


Open Top Types NP445

Specifications / Material and Finish
(see above)

Features

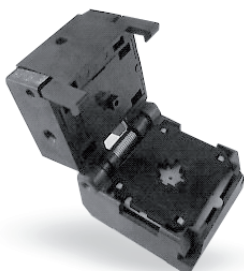
- Centre Contact available for exposed pads



Clamshell Type IC549 and IC550
Specifications / Material and Finish
(see above)

Features

- Centre Contact available for exposed pads, heat sink and floating base non sticking option
- Accommodates 0.5 ~1.2mm thick package

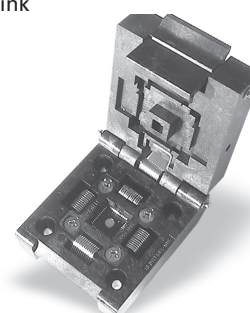


Clamshell Type QFN11T

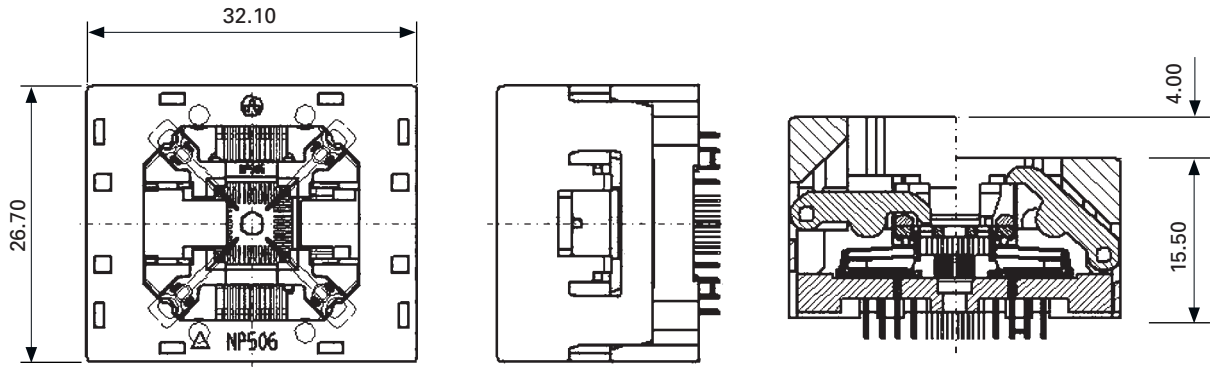
Specifications / Material and Finish
(see above)

Features

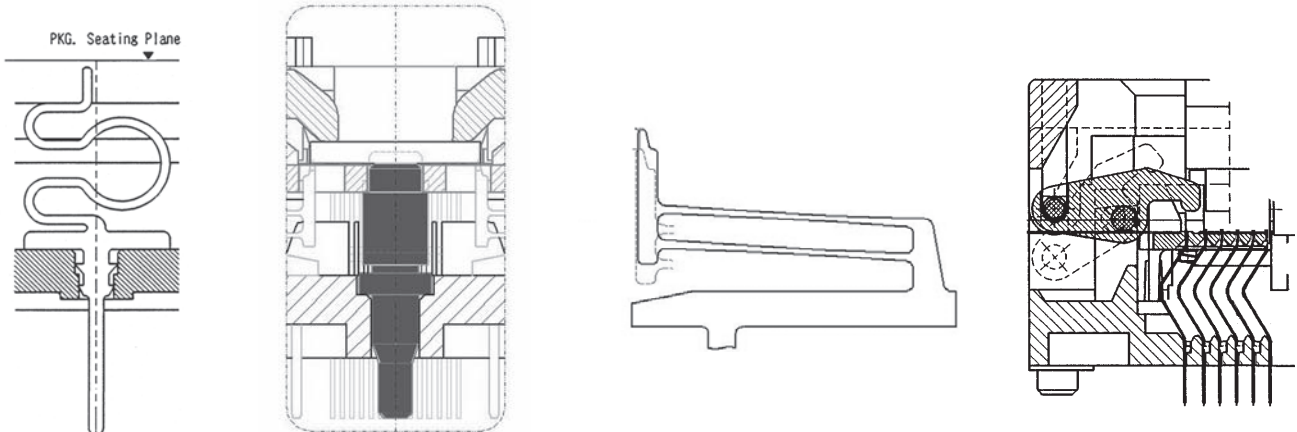
- Centre Contact available for exposed pads
- Probe Pins
- Heat sink



Typical (NP506) Open Top Socket Dimensions



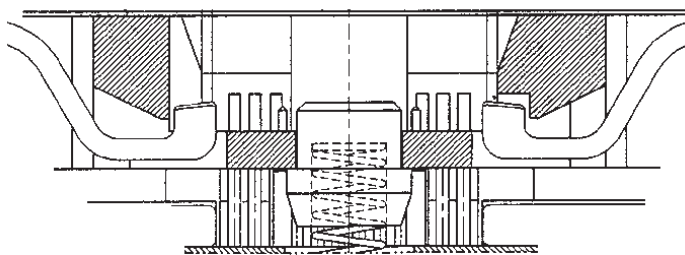
Contact Types



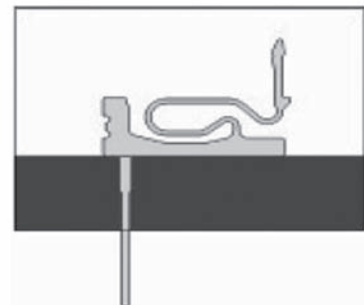
Centre Spring Types

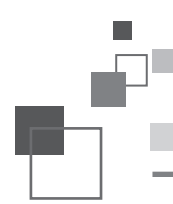
Low Wiping Type

Buckling Beam Type

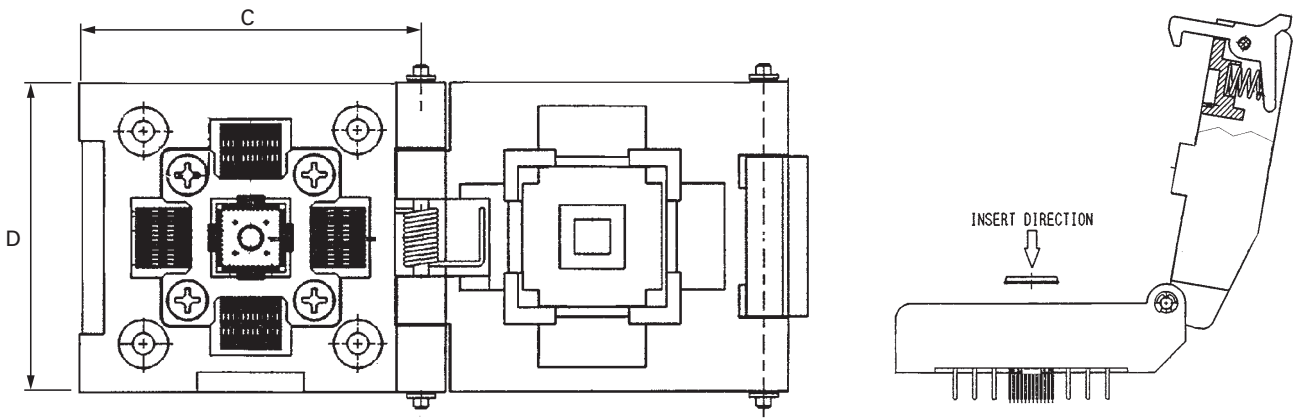


Standard Contact Type

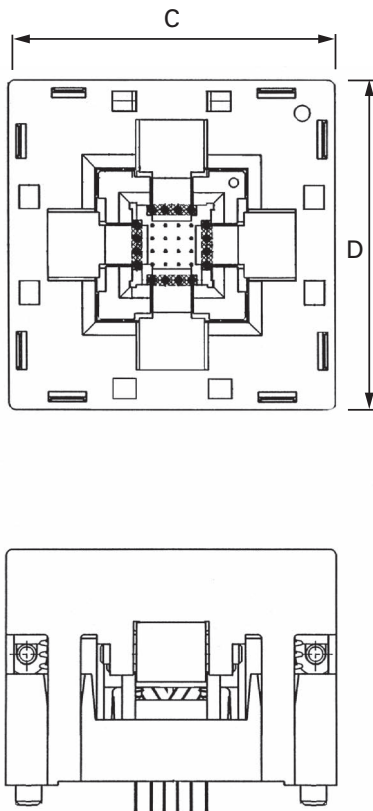




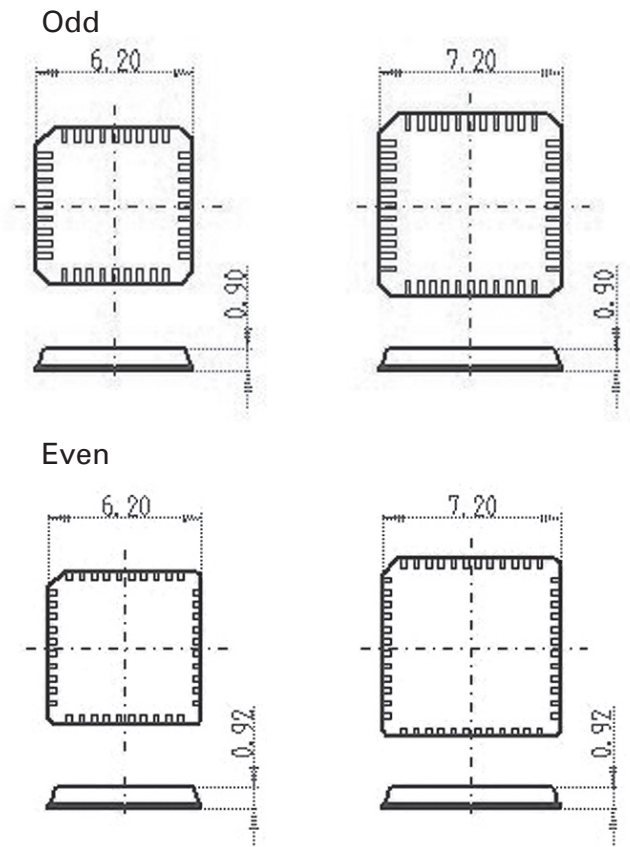
□ Typical Clamshell Socket Dimensions



□ Typical (NP404) Open Top Socket



□ Package Outline



QFN